

XFP 10G Dual LC Optical Transceivers

INTRODUCTION

This design guide provides the information needed to incorporate OptixCom's fiber optics transceiver products in the customer's system. The XFP series of transceiver products are compliant with the XFP multi-source agreement (MSA) INF-8077i (Rev. 4.5, 2005) and IEEE 802.3 Section 4 on "52. Physical Medium Dependent (PMD) sublayer and baseband medium, type 10GBASE-S (short wavelength serial), 10GBASE-L (long wavelength serial), and 10GBASE-E (extra long wavelength serial)". For more detail information, please refer to the URL <http://www.xfpmsa.org> or visit OptixCom web site: <http://www.OptixCom.com> for the official documentation.

The reference guide covers the following topics:

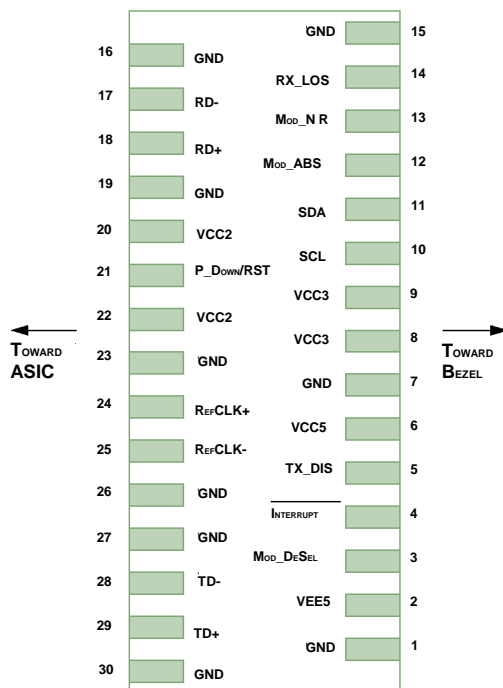
- A. PIN ASSIGNMENT & DESCRIPTION
- B. RECOMMENDED INTERFACE CIRCUIT
- C. PACKAGE OUTLINE
- D. SFP TRANSCEIVER HOST BOARD MECHANICAL LAYOUT
- E. ELECTRICAL CONNECTOR MECHANICAL LAYOUT
- F. CONNECTOR INSERTION, EXTRACTION, AND RETENTION FORCE
- G. TIMING REQUIREMENTS



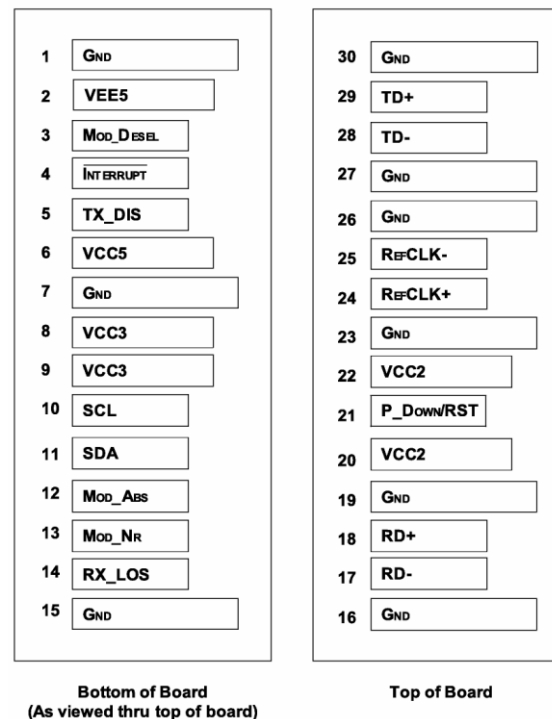
A. PIN ASSIGNMENT & DESCRIPTION

The XFP transceiver contains a printed circuit board that mates with the electrical connector. The pads are designed for a sequenced mating in the following order: ground contacts, power contacts, and signal contacts.

Host Board Connector Pad Layout



XFP Transceiver Pad Layout



Optical Transceivers Design Reference Guide



| Pin | Logic | Symbol | Name/Description | Note |
|-----|------------|------------|---|------|
| 1 | | GND | Module Ground | 1 |
| 2 | | VEE5 | Optional -5.2V Power Supply | |
| 3 | LVTTTL-I | Mod_DeSel | Module De-select; When held low allows module to respond to 2-wire serial interface | |
| 4 | LVTTTL-O | Interrupt | Interrupt; Indicates presence of an important condition which can be read over the 2-wire serial interface | 2 |
| 5 | LVTTTL-I | TX_DIS | Transmitter Disable; Turns off transmitter laser output | |
| 6 | | VCC5 | +5V Power Supply | |
| 7 | | GND | Module Ground | 1 |
| 8 | | VCC3 | +3.3V Power Supply | |
| 9 | | VCC3 | +3.3V Power Supply | |
| 10 | LVTTTL-I/O | SCL | 2-Wire Serial Interface Clock | 2 |
| 11 | LVTTTL-I/O | SDA | 2-Wire Serial Interface Data Line | 2 |
| 12 | LVTTTL-O | Mod_Abs | Indicates Module is not present. Grounded in the Module | 2 |
| 13 | LVTTTL-O | Mod_NR | Module Not Ready; Indicating Module Operational Fault | 2 |
| 14 | LVTTTL-O | RX_LOS | Receiver Loss Of Signal Indicator | 2 |
| 15 | | GND | Module Ground | 1 |
| 16 | | GND | Module Ground | 1 |
| 17 | CML-O | RD- | Receiver Inverted Data Output | |
| 18 | CML-O | RD+ | Receiver Non-Inverted Data Output | |
| 19 | | GND | Module Ground | 1 |
| 20 | | VCC2 | +1.8V Power Supply | 3 |
| 21 | LVTTTL-I | P_Down/RST | Power down; When high, requires the module to limit power consumption to 1.5W or below. 2-Wire serial interface must be functional in the low power mode. Reset; The falling edge initiates a complete reset of the module including the 2-wire serial interface, equivalent to a power cycle. | |
| 22 | | VCC2 | +1.8V Power Supply | 3 |
| 23 | | GND | Module Ground | 1 |
| 24 | PECL-I | RefCLK+ | Reference Clock Non-Inverted Input, AC coupled on the host board | |
| 25 | PECL-I | RefCLK- | Reference Clock Inverted Input, AC coupled on the host board | |
| 26 | | GND | Module Ground | 1 |
| 27 | | GND | Module Ground | 1 |
| 28 | CML-I | TD- | Transmitter Inverted Data Input | |
| 29 | CML-I | TD+ | Transmitter Non-Inverted Data Input | |
| 30 | | GND | Module Ground | 1 |

1. Module ground pins Gnd are isolated from the module case and chassis ground within the module.
2. Shall be pulled up with 4.7K-10Kohms to a voltage between 3. 15V and 3.45V on the host board.
3. The 1.8 V power supply can be optionally programmed to voltages lower than 1.8 V in modules supporting the variable power supply.

LOW SPEED ELECTRICAL HARDWARE PINS

In addition to the 2-wire serial interface the XFP module has the following low speed pins for control and status:

| | | | |
|---------|-----------|-------------|--------|
| Mod_NR | Mod_DeSel | Interrupt | TX_DIS |
| Mod_ABS | RX_LOS | P_Down/RST. | |

MOD_NR

The Mod_NR is an output pin that when High, indicates that the module has detected a condition that renders transmitter and or receiver data invalid, shall consist of logical OR of the following signals:

- Transmit Signal Conditioner Loss of Lock
- Transmitter Laser Fault
- Receiver Signal Conditioner Loss of Lock

Other conditions deemed valuable to the detection of fault may be added to the Mod_NR. The Mod_NR output pin is an open collector and must be pulled to Host_Vcc on the host board.

MOD_DESEL

The Mod_DeSel is an input pin. When held Low by the host, the module responds to 2-wire serial communication commands. The Mod_DeSel allows the use of multiple XFP modules on a single 2-wire interface bus. When the Mod_DeSel pin is "High", the module shall not respond to or acknowledge any 2-wire interface communication from the host. Mod_DeSel pin must be pulled to VCC3 in the module.

In order to avoid conflicts, the host system shall not attempt 2-wire interface communications within the Mod_DeSel assert time after any XFP modules are deselected. Similarly, the host must wait at least for the period of the Mod_DeSel deassert time before communicating with the newly selected module. The assertion and deassertion periods of different modules may overlap as long as the above timing requirements are met.

INTERRUPT

Interrupt is an output pin. When "Low", indicates possible module operational fault or a status critical to the host system. The Interrupt pin is an open collector output and must be pulled up to Host_Vcc the host board.

TX_DIS

TX_DIS is an input pin. When TX_DIS is asserted High, the XFP module transmitter output must be turned off. The TX_DIS pin must be pulled up to VCC3 in the XFP module.

MOD_ABS

Mod_ABS is pulled up to Host_Vcc on the host board and grounded in the XFP module. Mod_ABS is then asserted "High" when the XFP module is physically absent from a host slot.

RX_LOS

The RX_LOS when High indicates insufficient optical power for reliable signal reception. The RX_LOS pin is an open collector output and must be pulled up to Host_Vcc on the host board.

P_DOWN/RST

This is a multifunction pin for module Power Down and Reset. The P_Down/RST pin must be pulled up to VCC3 in the XFP module.

POWER DOWN FUNCTION

The P_Down pin, when held High by the host, places the module in the standby (Low Power) mode with a maximum power dissipation of 1.5W. This protects hosts which are not capable of cooling higher power modules which may be accidentally inserted.

The module's 2-wire serial interface and all laser safety functions must be fully functional in this low power mode. During P_Down, the module shall still support the completion of reset Interrupt, as well as maintain functionality of the variable power supply.

RESET FUNCTION

The negative edge of P_Down/RST signal initiates a complete module reset.

MODULE BEHAVIOR DURING POWER DOWN AND RESET

During execution of a reset (t_{init}) or while held in Power Down mode, a module may be unable to determine the correct value for Mod_NR and RX_LOS. These outputs as well as all interrupt related flags, except completion of Reset flag, shall be disregarded by the host. When the module completes a Reset and is not in Power Down mode, the module must represent the correct value of both signals on its outputs before posting a completion of reset interrupt to the host.

At no time shall a module cause spurious assertion of the Interrupt pin.

When a host initially applies power to a module with the P_Down/RST signal asserted, a module comes up in power down mode. The module shall only assert the Interrupt signal pin to inform the host it has completed a reset. The completion of reset flag shall be the only interrupt source flag set during power down mode. The host is expected to clear this interrupt before releasing the module from the power down mode. The transition from power down mode to normal mode will trigger a reset of the module and result in a 2nd module reset and a 2nd reset completion interrupt to the host

LOW SPEED ELECTRICAL SPECIFICATIONS

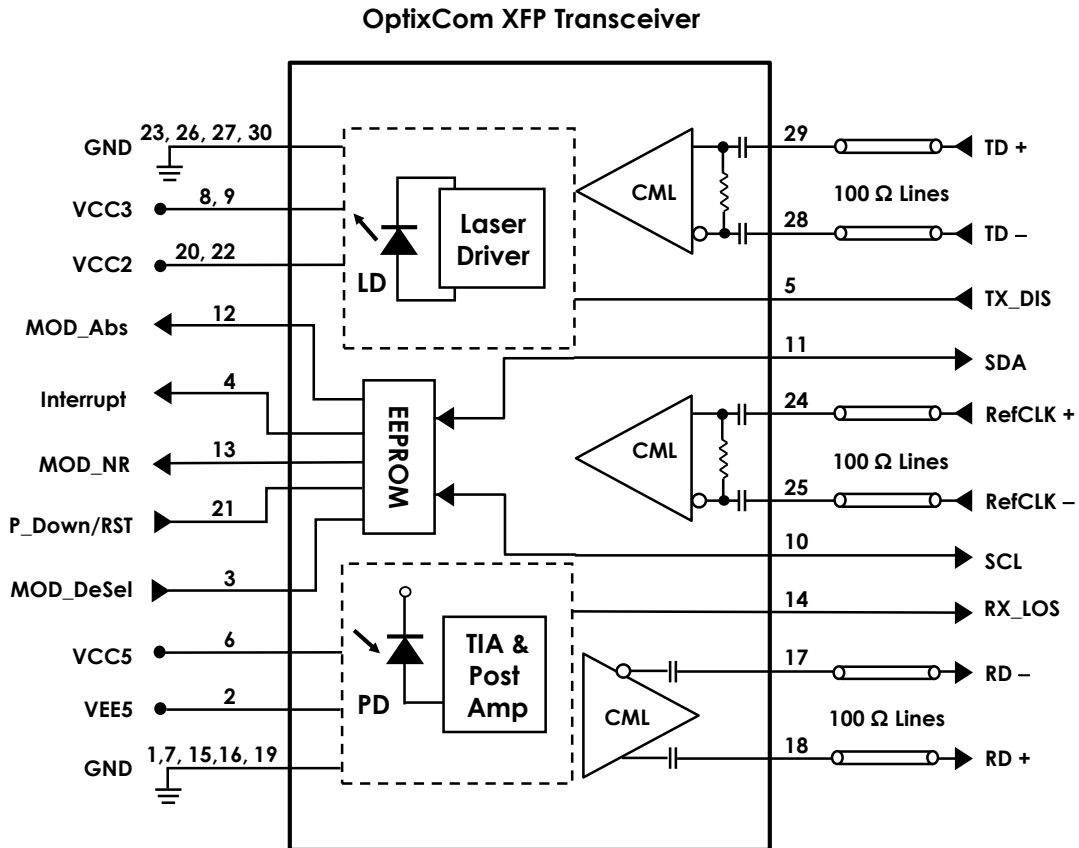
Low speed signaling is based on Low Voltage TTL (LVTTTL) operating at Vcc3 at a nominal supply of (3.3V± 5%). Hosts shall use a pull-up resistor connected to a host_Vcc of +3.3 volts (3.15 to 3.45 volts) on the 2-wire interface SCL (clock), SDA (Data), and all low speed status outputs.

The XFP low speed electrical specifications are given in the following. This specification ensures compatibility between host bus masters and XFP SCL/SDA lines and compatibility with I²C.

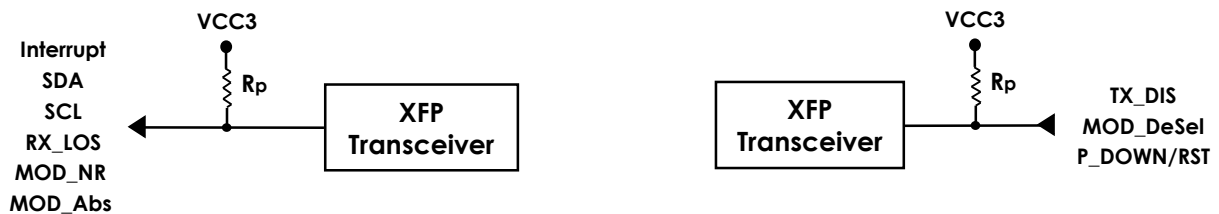
LOW SPEED CONTROL AND SENSE SIGNALS, ELECTRONIC CHARACTERISTICS

| Parameter | Symbol | Min. | Max. | Unit | Conditions |
|---|--------|----------------|----------------|------|---|
| XFP Interrupt, Mod_NR, RX_LOS | VoL | 0.0 | 0.40 | v | Rpullup pulled to host_Vcc, measured at host side of connector. IoL(max) = 3 mA |
| | VoH | host_Vcc - 0.5 | host_Vcc + 0.3 | v | Rpullup pulled to host_Vcc, measured at host side of connector. |
| XFP TX_Dis, P_Down/RST | ViL | -0.3 | 0.8 | v | Rpullup pulled to VCC3, measured at XFP side of connector. IiL(max) = -10 uA |
| | ViH | 2.0 | VCC3 + 0.3 | v | Rpullup pulled to VCC3, measured at XFP side of connector. IiH(max) = 10 uA |
| XFP SCL and SDA | VoL | 0.0 | 0.40 | v | Rpullup ¹ pulled to host_Vcc, measured at host side of connector. IoL(max) = 3 mA |
| | VoH | host_Vcc - 0.5 | host_Vcc + 0.3 | v | Rpullup ¹ pulled to host_Vcc, measured at host side of connector. |
| XFP SCL and SDA | ViL | -0.3 | Vcc3*0.3 | v | Rpullup ¹ pulled to Host_VCC, measured at XFP side of connector. IiL(max) = -10 uA |
| | ViH | Vcc3*0.7 | VCC3 + 0.5 | v | Rpullup ¹ pulled to Host_VCC, measured at XFP side of connector. IiH(max) = 10 uA |
| Leakage Current | Ii | -10 | 10 | µA | |
| Capacitance for XFP SCL and SDA I/O Pin | Ci | | 14 | pF | 10pF for XFP IC I/O pin, 4 pF for XFP PCB trace |
| Total bus capacitive load for SCL and for SDA | Cb | | 100 | pF | At 400 KHz, 3.0 Kohms Rp, max At 100 KHz, 8.0 Kohms Rp, max |
| | | | 400 | pF | At 400 KHz, 0.80 Kohms Rp, max At 100 KHz, 2.0 Kohms Rp, max |
| <p>1. For combinations of Rpullup (Rp), bus capacitance and speed, see Philips I²C specification revision 2.1, figures 39 and 44. Rise and fall time measurement levels are defined in the XFP management interface ac electrical specifications. Active bus termination may be used by the host in place of a pullup resistor, as described in the Philips I²C specification</p> | | | | | |

B. RECOMMENDED INTERFACE CIRCUIT



All the LVTTTL interface logic pins are open collector compatible. A pull up resistor R_p is used in the following scheme. The value of R_p is between $4.7K\Omega$ to $10K\Omega$.



The XFP host has 3 power supplies +1.8 V, +3.3 V, +5.0 V and an optional -5.2 V supply. The +1.8 V and +3.3 V supplies have two designated power pins in the connector for each power supply rail. The +5 V and -5.2 supplies have one designated power pin each. The maximum continuous or peak current carrying capacity for each connector pin is 500 mA.

The host system may alter the VCC2 supply to a voltage level lower than the nominal +1.8 V value. This mode of operation is optional and can be supported by modules and hosts that strive to meet lower power/current requirements. Modules supporting this optional lower power mode must be backwards compatible with modules and hosts supporting only 1.8 V on VCC2, i.e. modules implementing these optional modes must be able to operate normally with a voltage of +1.8 V applied on their VCC2 pins (albeit with higher power dissipation). XFP module maximum power dissipation must meet one of the following classes:

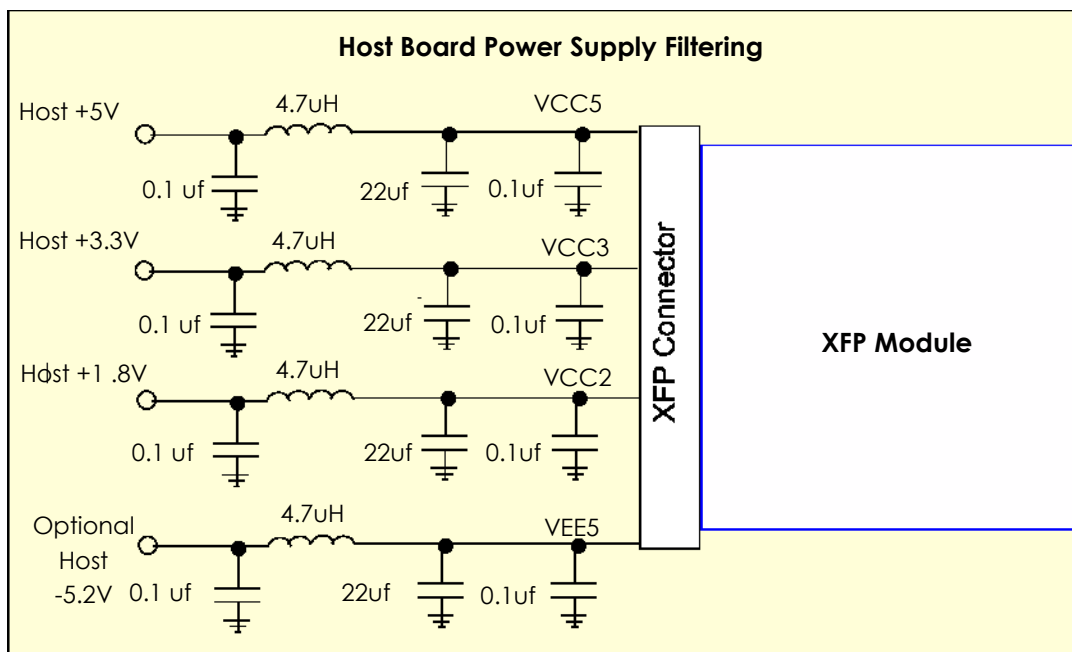
- Power Level 1 modules – Up to 1.5 W
- Power Level 2 modules – Up to 2.5 W
- Power Level 3 modules – Up to 3.5 W
- Power Level 4 modules – Greater than 3.5 W

To avoid exceeding system power supply limits and cooling capacity, the module may be placed in the power down mode by pulling pin 21 High. This guarantees module operating in Low Power mode with maximum power dissipation of $\leq 1.5W$.

A host board together with XFP module(s) forms an integrated power system. The host supplies stable power to the module. The module limits electrical noise coupled back into the host and limits inrush charge/current during hot plug insertion.

The example host board power supply filtering shown below will meet the noise filtering requirements in most systems. Other filtering implementations or local regulation may be used to meet the power noise output requirements described in Section 2.7.1 of XFP MSA document.

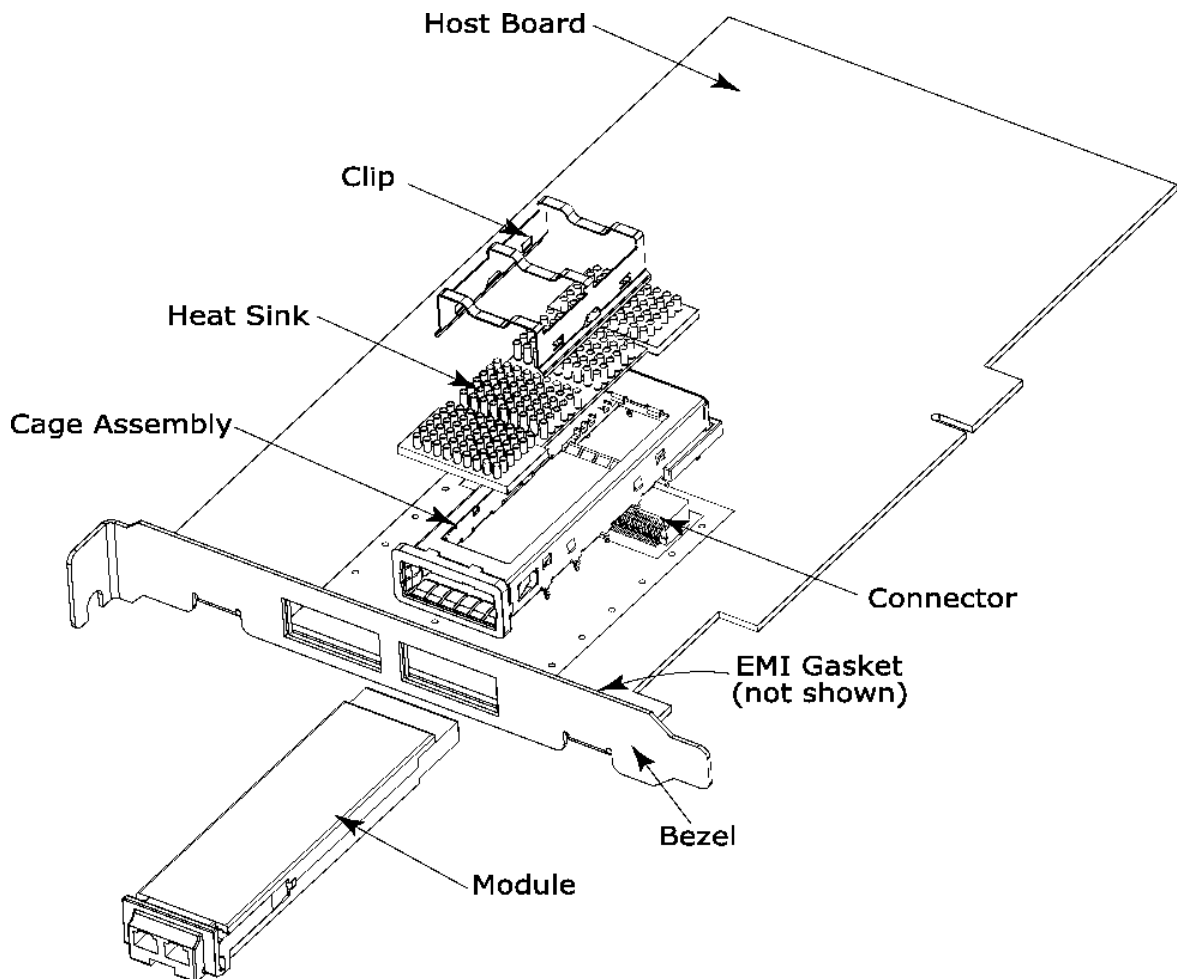
Any voltage drop across a filter network on the host is counted against the Host DC set point accuracy specification in Table 4 of XFP MSA . For this reason, the example filter may not be appropriate for a host powering multiple XFPs and/or other host components from a shared voltage supply.



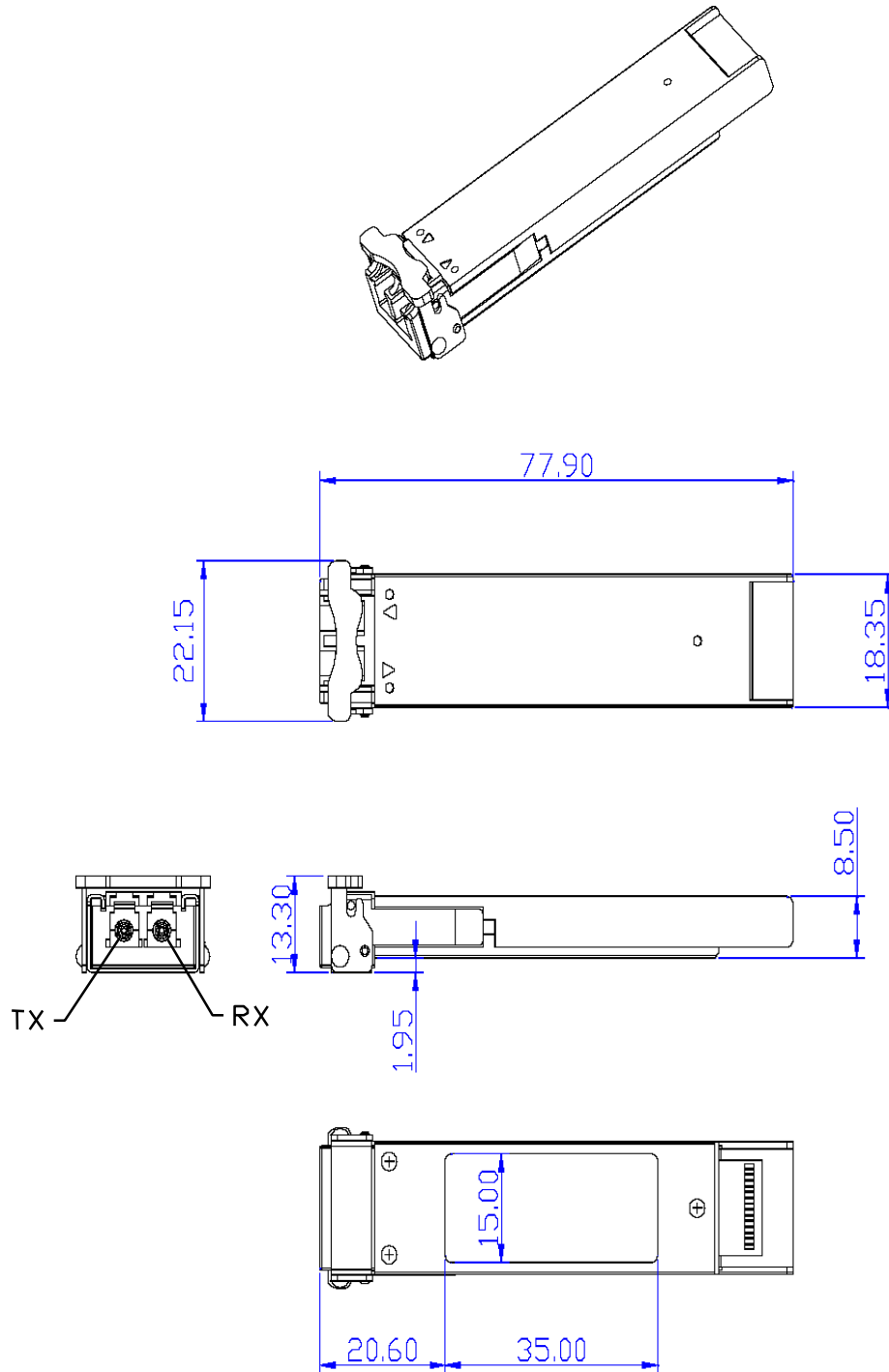
C. PACKAGE OUTLINE

The mechanical components defined in this section are illustrated in the following. The module, clip and connector dimensions are constant for all applications. While the bezel, cage assembly, EMI gasket and heat sink can be designed and/or adjusted for the individual application. The relatively small form factor of the XFP module combined with an adaptable heatsink option allows host system design optimization of module location, heat sink shape/dimension/fins design, and airflow control. The module can be inserted and removed from the cage with the heat sink and clip attached. Please note that OptixCom only offers the XFP transceiver module but not other components. Refer to XFP MSA document for more details of the other components.

XFP Mechanical Components



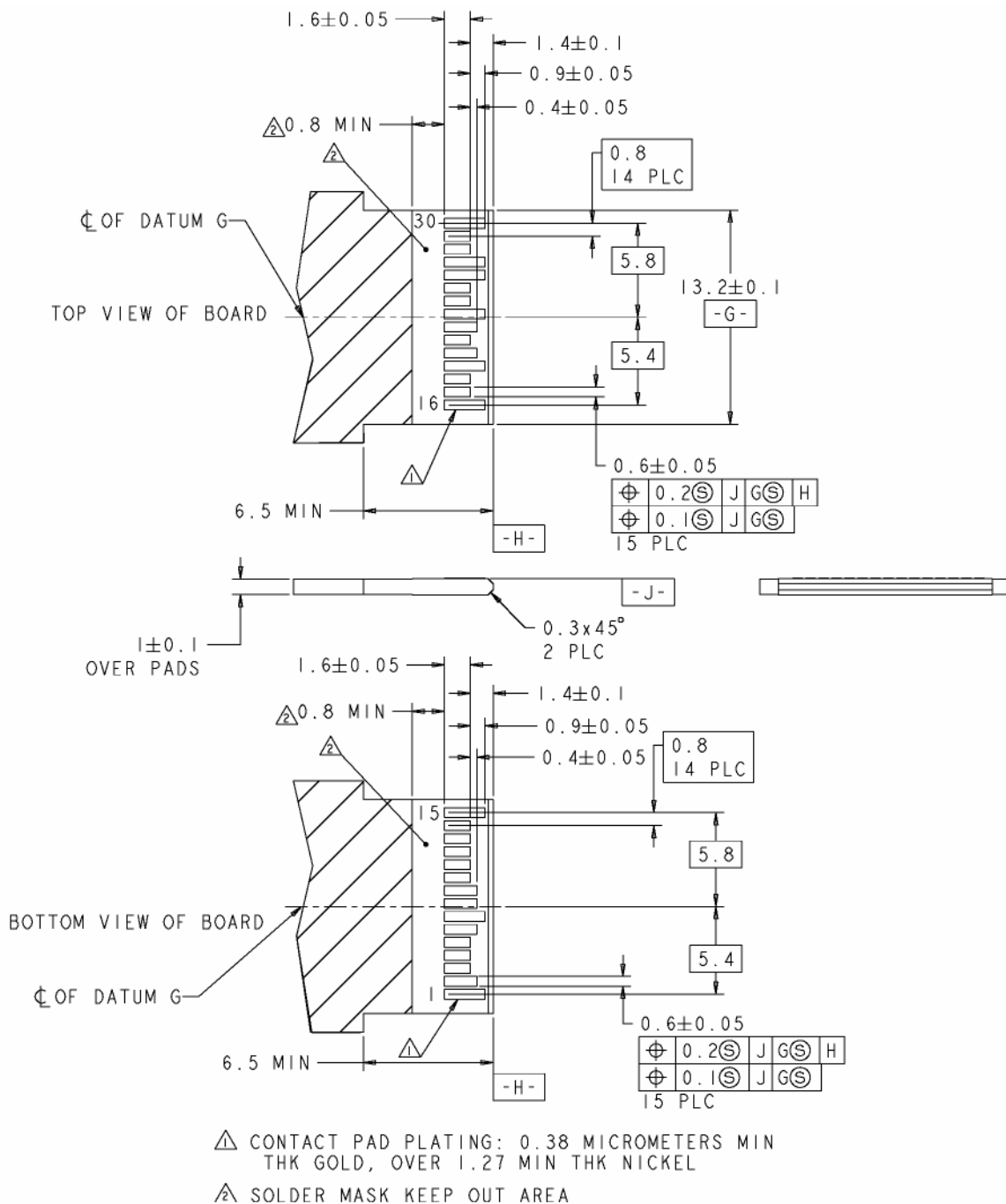
Mechanical Outline Dimensions



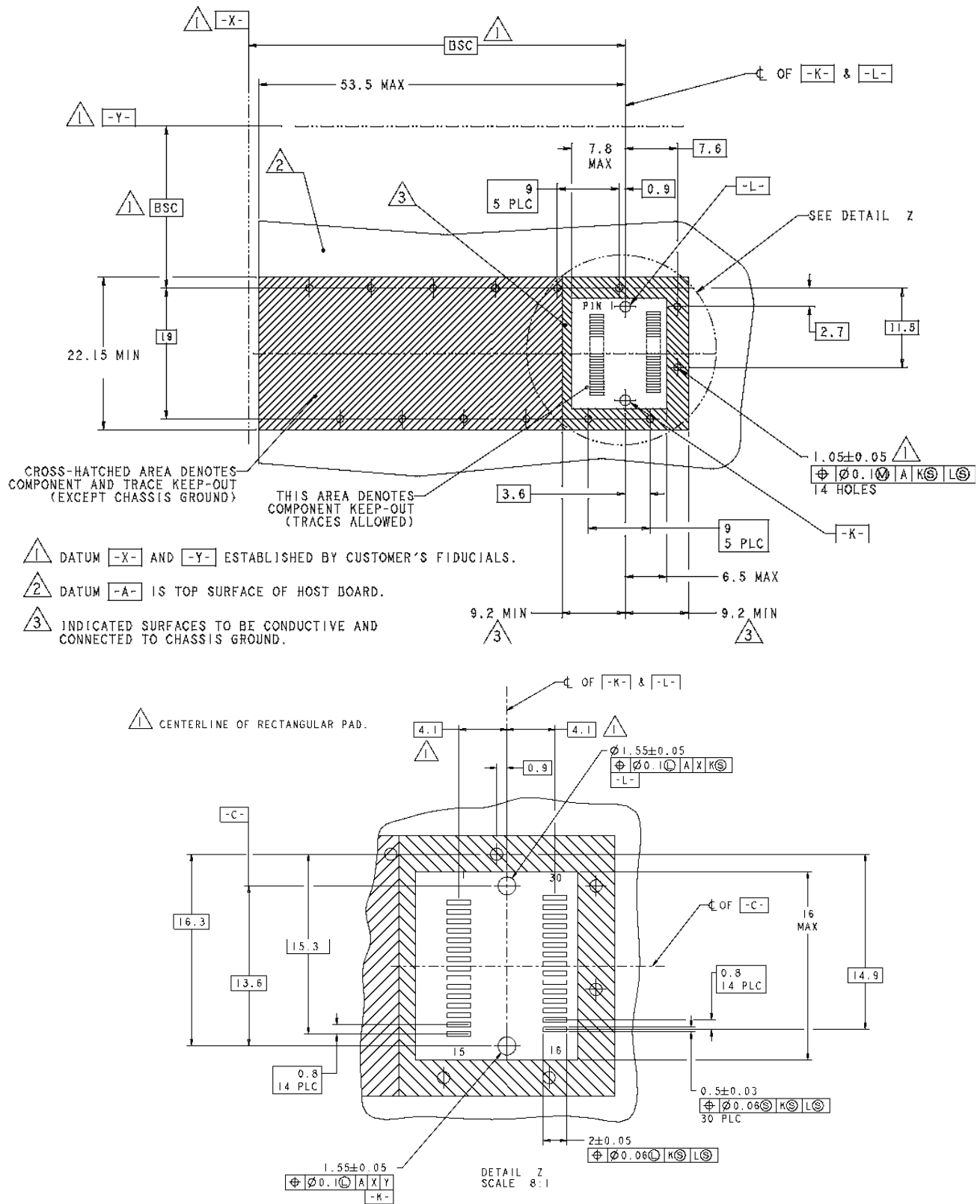
Unit: mm, typical tolerance for these dimensions is ± 0.2 mm

D. XFP TRANSCEIVER HOST BOARD MECHANICAL LAYOUT

The design of the mating portion of the transceiver printed circuit board and the electrical pad layout is illustrated in the following. The recommended contact pad plating for the printed circuit board is 0.38 micrometers minimum gold over 1.27 micrometers minimum thick nickel.

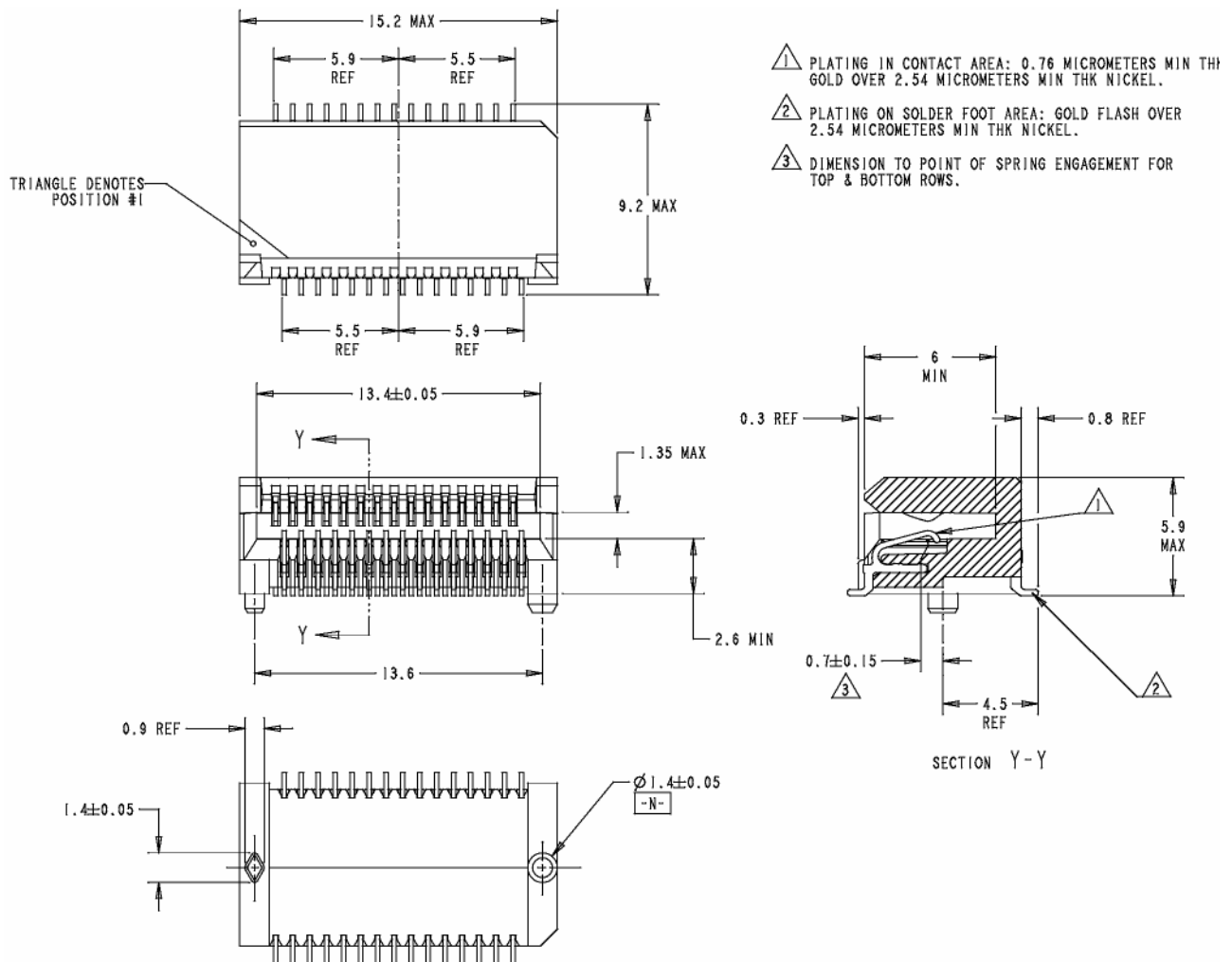


Optical Transceivers Design Reference Guide



E. ELECTRICAL CONNECTOR MECHANICAL LAYOUT

The XFP Connector is a 30-contact, right angle surface mount connector and available from several manufacturers¹. An example connector such as 788862-2 manufactured by Tyco is shown in the following. Newer versions of this connector are available from Tyco, Molex, and Harting with improved electrical performance.



F. CONNECTOR INSERTION, EXTRACTION, AND RETENTION FORCE

The requirement for the various functional forces and the durability cycles are specified in the following Table.

| Measurement | Minimum | Maximum | Units | Comments |
|---|----------------|----------------|--------------|---|
| XFP transceiver insertion | 0 | 40 | Newtons | |
| XFP transceiver extraction | 0 | 30 | Newtons | |
| XFP transceiver retention | 90 | N/A | Newtons | No damage to transceiver below 90N |
| Cage retention (Latch strength) | 180 | N/A | Newtons | No damage to the latch below 180N |
| Cage retention in Host Board | 133 | N/A | Newtons | Force to be applied in a vertical direction with no damage to the cage. |
| Insertion / removal cycles, connector/cage | 100 | N/A | cycles | |
| Insertion / removal cycles, XFP Transceiver | 50 | N/A | cycles | |

G. TIMING REQUIREMENTS OF CONTROL AND STATUS I/O

LOW SPEED ELECTRICAL HARDWARE PINS

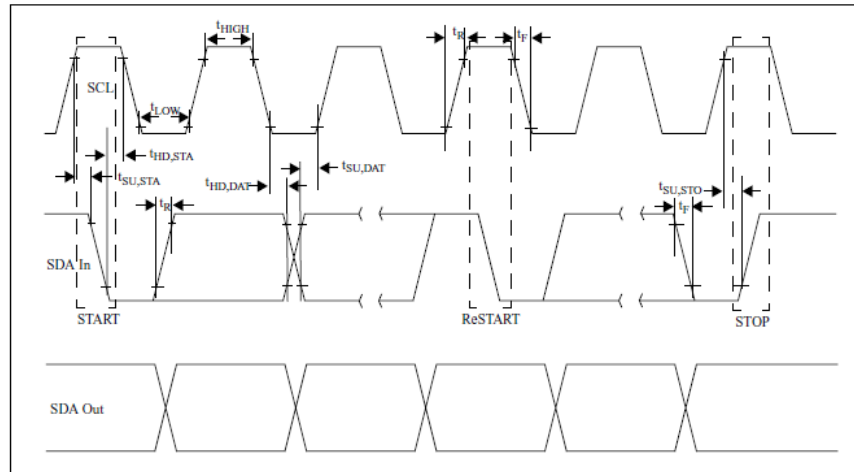
The timing requirements of the control and status lines are listed in Table 3 of XFP MSA document. They are summarized in the Table below. The 2-wire serial bus timing is described in Chapter 4: XFP 2-Wire Interface Protocol in XFP MSA document.

Timing Requirements of Control and Status I/O

| <i>Parameter</i> | <i>Symbol</i> | <i>Min.</i> | <i>Max.</i> | <i>Unit</i> | <i>Conditions</i> |
|-------------------------|---------------|-------------|-------------|-------------|--|
| TX_DIS assert time | t_off | | 10 | tsec | rising edge of TX_DIS to fall of output signal below 10% of nominal |
| TX_DIS negate time | t_on | | 2 | msec | Falling edge of TX_DIS to rise of output signal above 90% of nominal |
| Time to initialize | t_init | | 300 | msec | From power on or hot plug after supply meeting Table 4 or from falling edge of P_Down/RST. |
| Interrupt assert delay | Interrupt_on | | 200 | msec | From occurrence of the condition triggering Interrupt |
| Interrupt negate delay | Interrupt_off | | 500 | tsec | From clear on read Interrupt flags |
| P_Down/RST assert delay | P_Down/RST_on | | 100 | tsec | From Power down initiation |
| Mod_NR assert delay | Mod_nr_on | | 1 | msec | From Occurrence of fault to assertion of MOD_NR |
| Mod_NR negate delay | Mod_nr_off | | 1 | msec | From clearance of signal to negation of MOD_NR |
| P-Down reset time | | 10 | | tsec | Min length of P-Down assert to initiate reset |
| RX_LOS assert delay | t_loss_on | | 100 | tsec | From Occurrence of loss of signal to assertion of RX_LOS |
| RX_LOS negate delay | t_loss_off | | 100 | tsec | From Occurrence of presence of signal to negation of RX_LOS |

2-WIRE TIMING DIAGRAM AND SPECIFICATIONS

XFP is positioned to leverage 2-wire timing (Fast Mode devices) to align the use of related cores on host ASICs. XFP 2-wire bus timing and AC specifications are shown in the following.



| Parameter | Symbol | Min. | Max. | Unit | Conditions |
|---|---------------------|------|------|------|---|
| Clock Frequency | f _{SCL} | 0 | 400 | kHz | |
| Clock Pulse Width Low | t _{LOW} | 1.3 | | μs | |
| Clock Pulse Width High | t _{HIGH} | 0.6 | | μs | |
| Time bus free before new transmission can start | t _{BUF} | 20 | | μs | Between STOP and START |
| START Hold Time | t _{HD,STA} | 0.6 | | μs | |
| START Set-up Time | t _{SU,STA} | 0.6 | | μs | |
| Data In Hold Time | t _{HD,DAT} | 0 | | μs | |
| Data In Set-up Time | t _{SU,DAT} | 0.1 | | μs | |
| Input Rise Time (100kHz) | t _{R,100} | | 1000 | ns | From (V _{IL,MAX} - 0.15) to (V _{IH,MIN} + 0.15) |
| Input Rise Time (400kHz) | t _{R,400} | | 300 | ns | From (V _{IL,MAX} - 0.15) to (V _{IH,MIN} + 0.15) |
| Input Fall Time (100kHz) | t _{F,100} | | 300 | ns | From (V _{IH,MIN} + 0.15) to (V _{IL,MAX} - 0.15) |
| Input Fall Time (400kHz) | t _{F,400} | | 300 | ns | From (V _{IH,MIN} + 0.15) to (V _{IL,MAX} - 0.15) |
| STOP Set-up Time | t _{SU,STO} | 0.6 | | μs | |
| Host Supplied Module DeSelect Setup Time | Host_select_setup | 2 | | ms | Setup time on the select lines before start of a host initiated serial bus sequence |
| Host Supplied Module DeSelect Hold Time | Host_select_hold | 10 | | μs | Delay from completion of a serial bus sequence to changes of transceiver select status |
| Aborted sequence - bus release | Deselect_Abort | | 2 | ms | Delay from a host asserting Mod_DeSel (at any point in a bus sequence), to the XFP module releasing SCL and SDA |